2SD2046

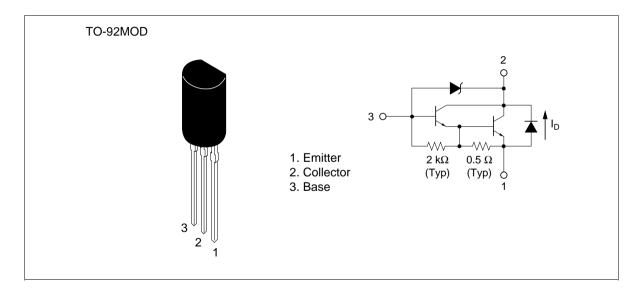
Silicon NPN Epitaxial, Darlington

HITACHI

Application

Low frequency power amplifier

Outline





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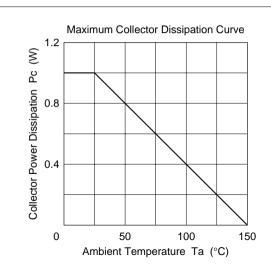
Absolute Maximum Ratings (Ta = 25°C)

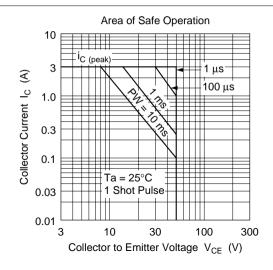
Item	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	50	V
Emitter to base voltage	V_{EBO}	7	V
Collector current	I _c	1.5	A
Collector peak current	ic _(peak)	3.0	A
Collector power dissipation	P _c	1.0	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C
E to C diode forward current	I _D	1.5	A

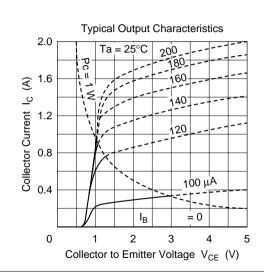
Electrical Characteristics ($Ta = 25^{\circ}C$)

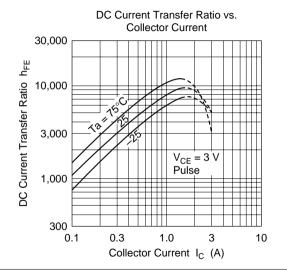
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage (Zener breakdown voltage)	V _{(BR)CBO} (V _z)	50	60	70	V	$I_{c} = 0.1 \text{ mA}, I_{e} = \infty$
Collector to emitter breakdown voltage	$V_{\text{(BR)CEO}}$	50	_	_	V	I_{C} = 10 mA, R_{BE} = ∞
Emitter to base breakdown voltage	$V_{(BR)EBO}$	7	_	_	V	$I_{E} = 50 \text{ mA}, I_{C} = 0$
Collector cutoff current	I _{CEO}	_	_	10	μΑ	$V_{CE} = 40 \text{ V}, R_{BE} = \infty$
DC current transfer ratio	h _{FE}	2000	_	10000		$V_{CE} = 3 \text{ V}, I_{C} = 1 \text{ A}^{*1}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)1}}$	_	_	1.5	V	$I_{\rm C} = 1 \text{ A}, I_{\rm B} = 1 \text{ mA*}^{1}$
	V _{CE(sat)2}	_	_	2.0	V	$I_{\rm C} = 1.5 \text{ A}, I_{\rm B} = 1.5 \text{ mA}^{*1}$
Base to emitter saturation voltage	$V_{BE(sat)1}$	_	_	2.0	V	$I_{C} = 1 \text{ A}, I_{B} = 1 \text{ mA*}^{1}$
	$V_{BE(sat)2}$	_	_	2.5	V	$I_{\rm C}$ = 1.5 A, $I_{\rm B}$ = 1.5 mA* ¹
E to C diode forward voltage	V _D	_	_	3.0	V	I _D = 1.5 A* ¹

Note: 1. Pulse test

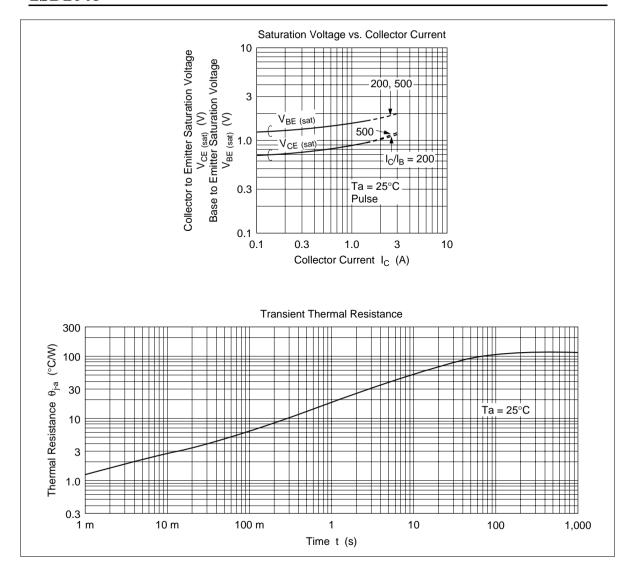




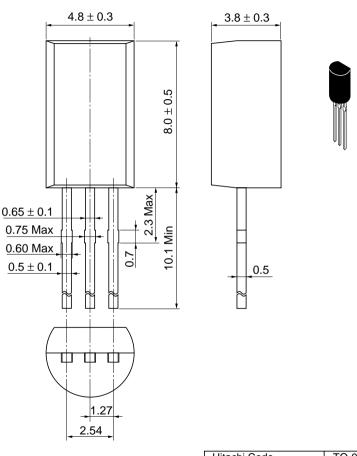




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Unit: mm



Hitachi Code TO-92 Mod

JEDEC —

EIAJ Conforms

Weight (reference value) 0.35 g

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